July 2005

CNY17-1, CNY17-3, CNY17-2, CNY17-4 Phototransistor Optocouplers

Features

- CNY17-1/2/3 are also available in white package by specifying -M suffix (eg. CNY17-2-M)
- UL recognized (File # E90700)
- VDE recognized
  - 102497 for white package
  - Add option V for white package (e.g., CNY17-2V-M)
  - File #102497
  - Add option '300' for black package (e.g., CNY17-2.300)
  - File #94766
- Current transfer ratio in select groups
- High BV_{CEO}—70V minimum

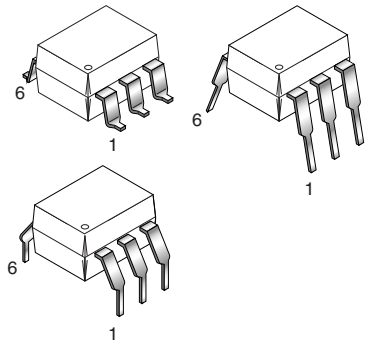
Applications

- Power supply regulators
- Digital logic inputs
- Microprocessor inputs
- Appliance sensor systems
- Industrial controls

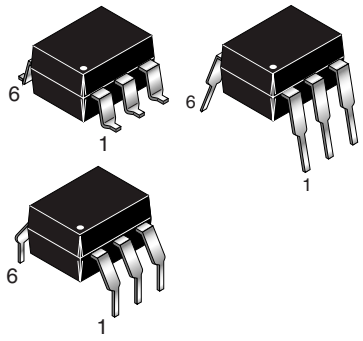
Description

The CNY17 series consists of a Gallium Arsenide IRED coupled with an NPN phototransistor.

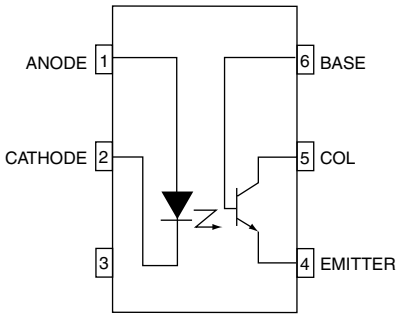
White Package (-M Suffix)



Black Package (No -M Suffix)



Schematic



Parameters	Symbol	Device	Value	Units
TOTAL DEVICE				
Storage Temperature	T_{STG}	All	-55 to +150	°C
Operating Temperature	T_{OPR}	All	-55 to +100	°C
Lead Solder Temperature	T_{SOL}	All	260 for 10 sec	°C
Total Device Power Dissipation @ 25°C (LED plus detector)	P_D	-M	250	mW
		non -M	260	
Derate Linearly From 25°C		-M	2.94	mW/°C
		non -M	3.50	
EMITTER				
Continuous Forward Current	I_F	-M	60	mA
		non -M	90	
Reverse Voltage	V_R	All	6	V
Forward Current - Peak (1 µs pulse, 300 pps)	I_F (pk)	-M	1.5	A
		non -M	3.0	
LED Power Dissipation 25°C Ambient	P_D	-M	120	mW
		non -M	135	
Derate Linearly From 25°C		-M	1.41	mW/°C
		non -M	1.8	
DETECTOR				
Detector Power Dissipation @ 25°C	P_D	-M	150	mW
		non -M	200	
Derate Linearly from 25°C		-M	1.76	mW/°C
		non -M	2.67	

Electrical Characteristics (T_A = 25°C Unless otherwise specified.)

Individual Component Characteristics

Parameters	Test Conditions	Symbol	Device	Min	Typ	Max	Units
EMITTER							
Input Forward Voltage	I_F = 60 mA	V_F	-M		1.35	1.65	V
	I_F = 10 mA		non -M		1.15	1.50	
Capacitance	V_F = 0 V, f = 1.0 MHz	C_J	non -M		50		pF
			-M		18		
Reverse Leakage Current	V_R = 6 V	I_R	All		0.001	10	µA
DETECTOR							
Breakdown Voltage							
Collector to Emitter	I_C = 1.0 mA, I_F = 0	BV_{CEO}	All	70	100		V
Collector to Base	I_C = 10 µA, I_F = 0	BV_{CBO}	All	70	120		V
Emitter to Collector	I_E = 100 µA, I_F = 0	BV_{ECO}	All	7	10		V
Leakage Current							
Collector to Emitter	V_{CE} = 10 V, I_F = 0	I_{CEO}	All		1	50	nA
Collector to Base	V_{CB} = 10 V, I_F = 0	I_{CBO}	All			20	nA
Capacitance							
Collector to Emitter	V_{CE} = 0, f = 1 MHz	C_{CE}	All		8		pF
Collector to Base	V_{CB} = 0, f = 1 MHz	C_{CB}	All		20		pF
Emitter to Base	V_{EB} = 0, f = 1 MHz	C_{EB}	All		10		pF

Isolation Characteristics

Characteristic	Test Conditions	Symbol	Device	Min	Typ**	Max	Units
Input-Output Isolation Voltage	f = 60 Hz, t = 1 min.	V_{ISO}	Black Package	5300			Vac(rms)*
			'-M' White Package	7500			Vac(pk)
Isolation Resistance	V_{I-O} = 500 VDC	R_{ISO}	All	1011			Ω
Isolation Capacitance	V_{I-O} = Ø, f = 1 MHz	C_{ISO}	Black Package		0.5		pF
			'-M' White Package		0.2		

Note
* 5300 Vac(rms) for 1 minute equates to approximately 9000 Vac (pk) for 1 second
** Typical values at T_A = 25°C

Transfer Characteristics (T_A = 25°C Unless otherwise specified.)

DC Characteristics	Test Conditions	Symbol	Device	Min	Typ	Max	Units
Current Transfer Ratio, Collector to Emitter	I_F = 10 mA, V_{CE} = 5 V	CTR	CNY17-1/-1-M	40		80	%
			CNY17-2/-2-M	63		125	
			CNY17-3/-3-M	100		200	
			CNY17-4	160		320	
Saturation Voltage	I_F = 10 mA, I_C = 2.5 mA	$V_{CE(SAT)}$	All			.40	V
AC Characteristics	**Test Conditions**	**Symbol**	**Device**	**Min**	**Typ**	**Max**	**Units**
Non-Saturated Switching Times							
Turn-On Time (Fig.19 and Fig.20)	R_L = 100 Ω, I_C = 2 mA, V_{CC} = 10 V	t_{on}	non -M			10	µs
Turn-Off Time (Fig.19 and Fig.20)	R_L = 100 Ω, I_C = 2 mA, V_{CC} = 10 V	t_{off}	non -M			10	µs
Delay Time (Fig.19 and Fig.20)	I_F = 10 mA, V_{CC} = 5 V, R_L = 75 Ω	t_d	-M			5.6	µs
Rise Time (Fig.19 and Fig.20)	I_F = 10 mA, V_{CC} = 5 V, R_L = 75 Ω	t_r	-M			4.0	µs
Storage Time (Fig.19 and Fig.20)	I_F = 10 mA, V_{CC} = 5 V, R_L = 75 Ω	t_s	-M			4.1	µs
Fall Time (Fig.19 and Fig.20)	I_F = 10 mA, V_{CC} = 5 V, R_L = 75 Ω	t_f	-M			3.5	µs
Saturated Switching Times							
Turn-On Time (Fig.19 and Fig.20)	I_F = 20 mA, V_{CE} = 0.4 V	t_{on}	CNY17-1			5.5	µs
	I_F = 10 mA, V_{CE} = 0.4 V		CNY17-2, CNY17-3, CNY17-4			8.0	
Rise-Time (Fig.19 and Fig.20)	I_F = 20 mA, V_{CE} = 0.4 V	t_r	CNY17-1			4.0	µs
	I_F = 10 mA, V_{CE} = 0.4 V		CNY17-2, CNY17-3, CNY17-4			6.0	
	I_F = 20 mA, V_{CC} = 5 V, R_L = 1 KΩ		CNY17-1-M			4.0	
	I_F = 10 mA, V_{CC} = 5 V, R_L = 1 KΩ		CNY17-2-M, CNY17-3-M			6.0	
Delay Time (Fig.19 and Fig.20)	I_F = 20 mA, V_{CC} = 5 V, R_L =1 KΩ	t_d	CNY17-1-M			5.5	µs
	I_F = 10 mA, V_{CC} = 5 V, R_L =1 KΩ		CNY17-2, CNY17-3			8.0	
Turn-Off Time (Fig.19 and Fig.20)	I_F = 20 mA, V_{CE} = 0.4 V	t_{off}	CNY17-1			34.0	ms
	I_F = 10 mA, V_{CE} = 0.4 V		CNY17-2, CNY17-3, CNY17-4			39.0	

Transfer Characteristics (T_A = 25°C Unless otherwise specified.) (Continued)

DC Characteristics	Test Conditions	Symbol	Device	Min	Typ	Max	Units
Fall-Time (Fig. 19 and Fig. 20)	I_F = 20 mA, V_{CE} = 0.4V	t_f	CNY17-1			20.0	µs
	I_F = 10 mA, V_{CE} = 0.4V		CNY17-2, CNY17-3, CNY17-4			24.0	
	I_F = 20 mA, V_{CC} = 5V, R_L = 1KΩ		CNY17-1-M			20.0	
	I_F = 10 mA, V_{CC} = 5V, R_L = 1KΩ		CNY17-2-M, CNY17-3-M,			24.0	
Storage Time (Fig. 19 and Fig. 20)	I_F = 20 mA, V_{CC} = 5V, R_L = 1KΩ	t_s	CNY17-1-M			34.0	µs
	I_F = 10 mA, V_{CC} = 5V, R_L = 1KΩ		CNY17-2-M, CNY17-3-M,			39.0	

Fig.1 Normalized CTR vs. Forward Current (Black Package)

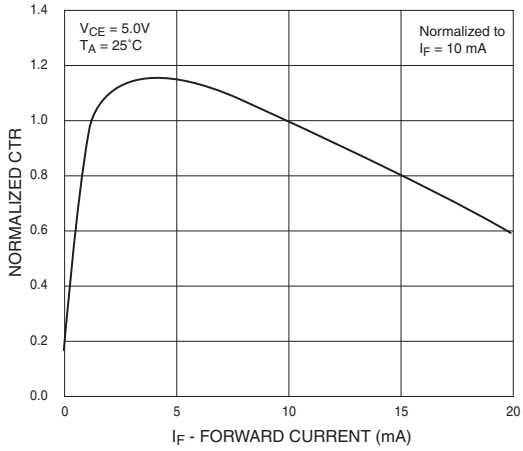


Fig.2 Normalized CTR vs. Forward Current (White Package)

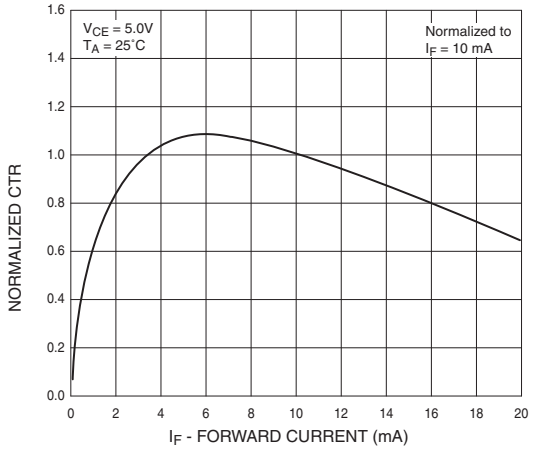


Fig. 3 Normalized CTR vs. Ambient Temperature (Black Package)

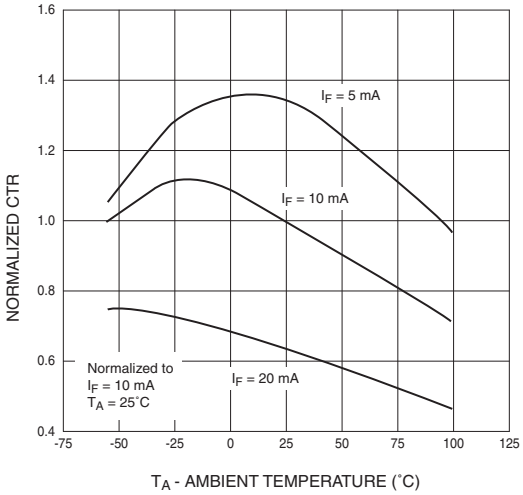


Fig. 4 Normalized CTR vs. Ambient Temperature (White Package)

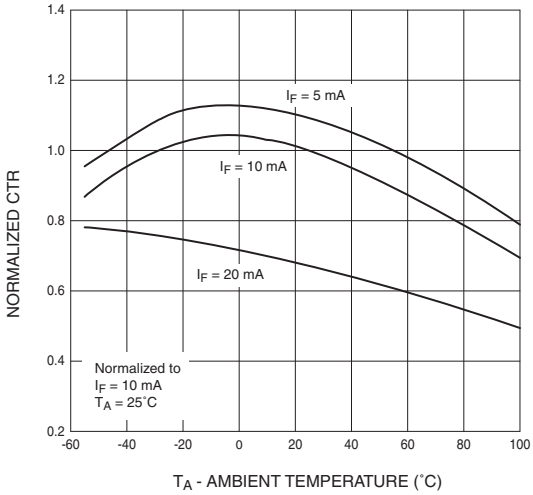


Fig. 5 CTR vs. RBE (Unsaturated) (Black Package)

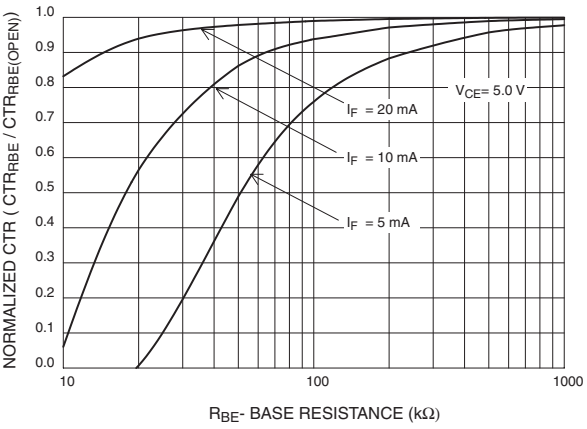


Fig. 6 CTR vs. RBE (Unsaturated) (White Package)

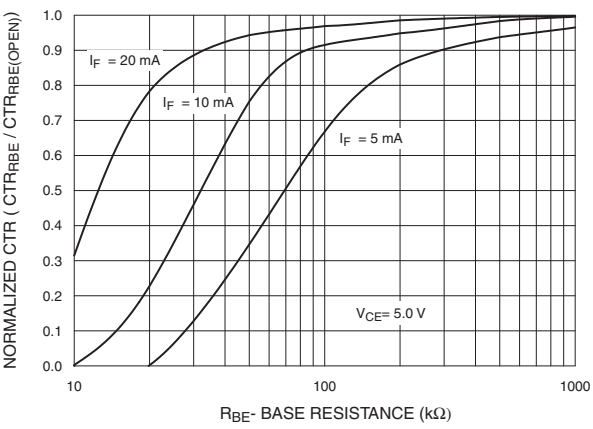


Fig. 7 CTR vs. RBE (Saturated) (Black Package)

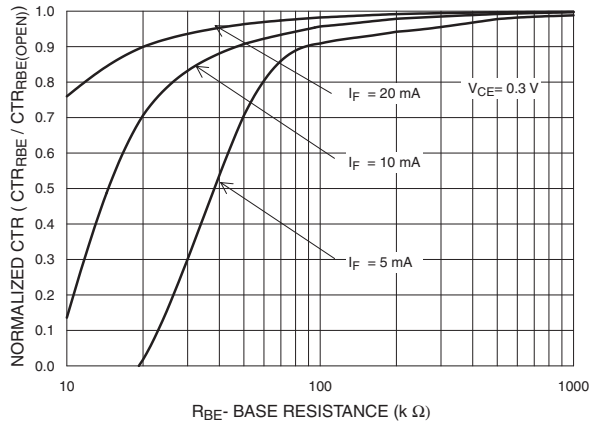


Fig. 8 CTR vs. RBE (Saturated) (White Package)

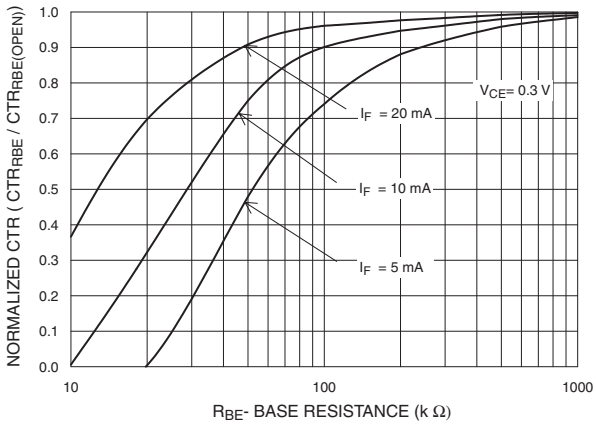


Fig. 9 Switching Speed vs. Load Resistor (Black Package)

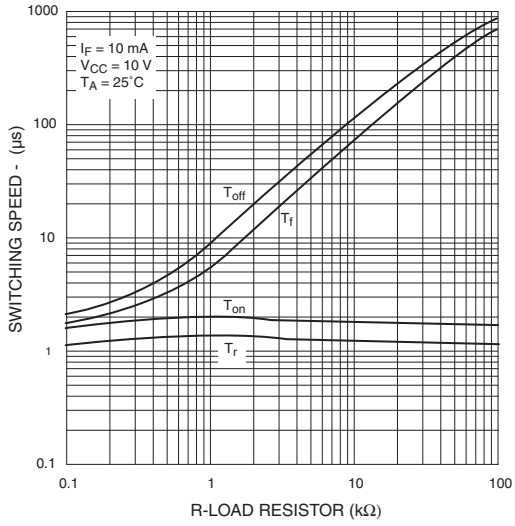


Fig. 10 Switching Speed vs. Load Resistor (White Package)

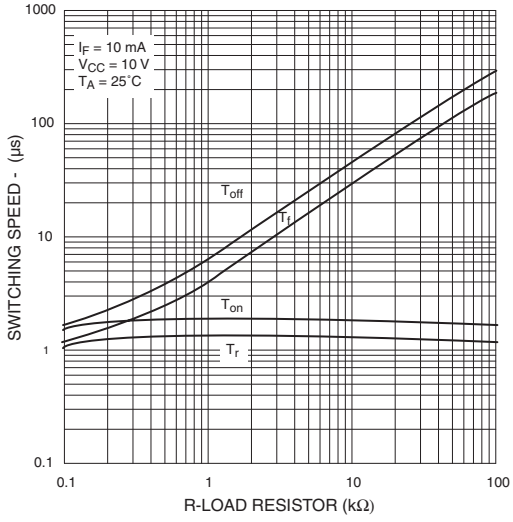


Fig. 11 Normalized t_{on} vs. R_{BE} (Black Package)

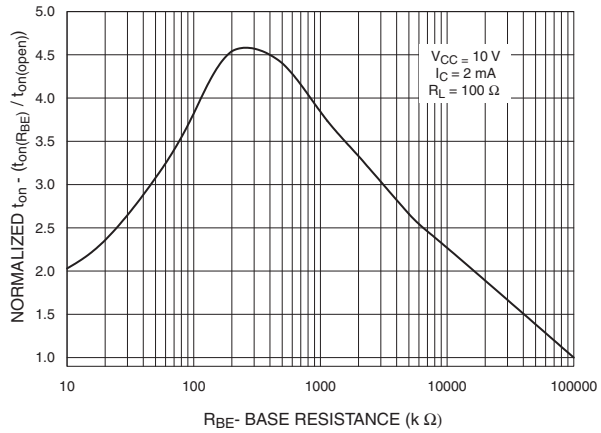


Fig. 12 Normalized t_{on} vs. R_{BE} (White Package)

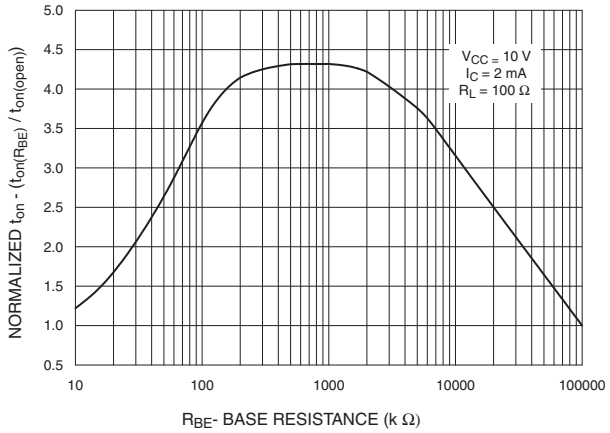


Fig. 13 Normalized t_{off} vs. R_{BE} (Black Package)

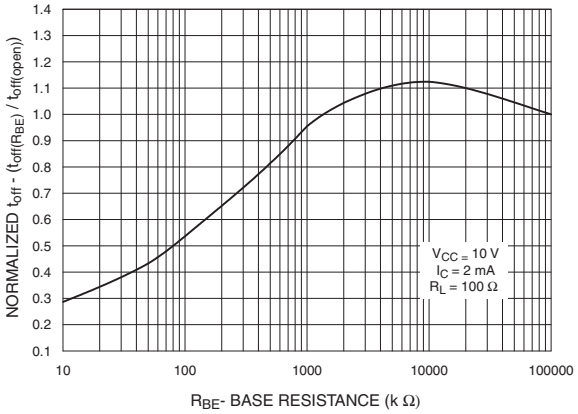


Fig. 14 Normalized t_{off} vs. R_{BE} (White Package)

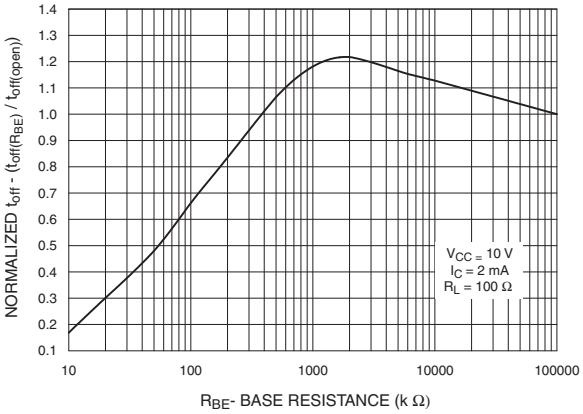


Fig. 15 LED Forward Voltage vs. Forward Current (Black Package)

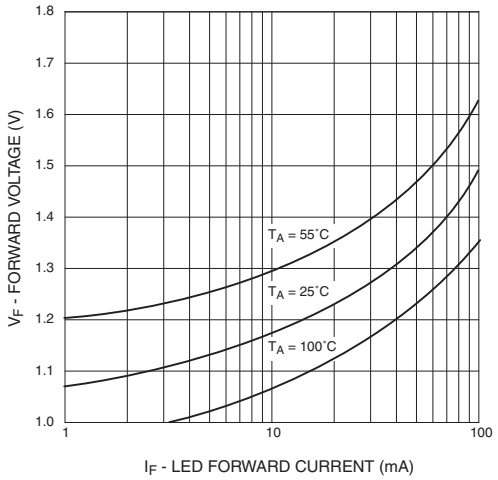


Fig. 16 LED Forward Voltage vs. Forward Current (White Package)

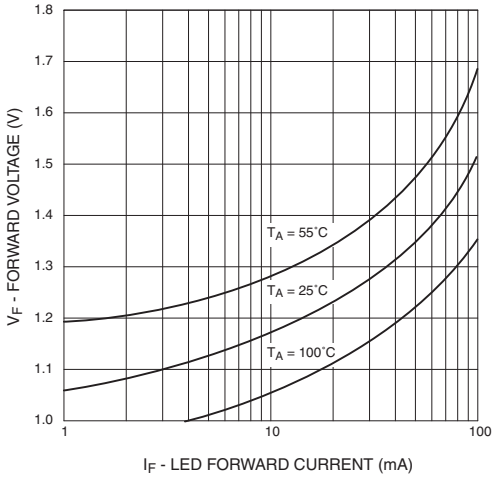


Fig. 17 Collector Current vs. Collector-Emitter Saturation Voltage

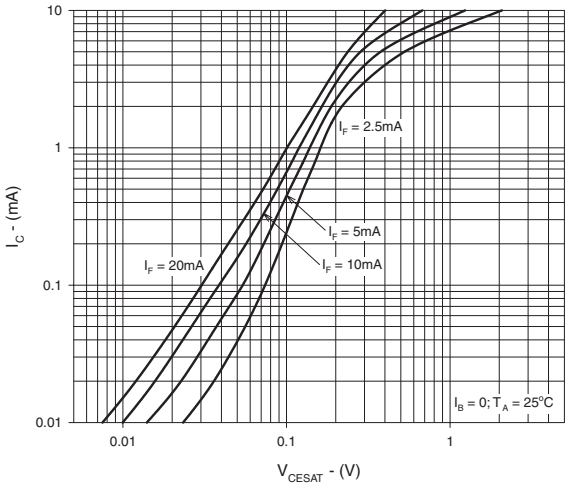
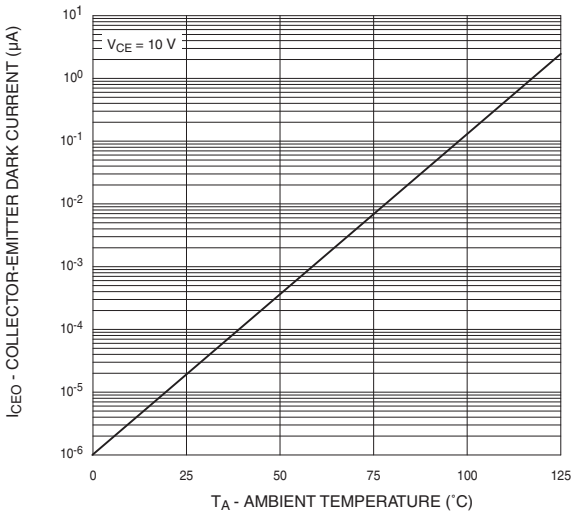


Fig. 18 Dark Current vs. Ambient Temperature (Black Package)



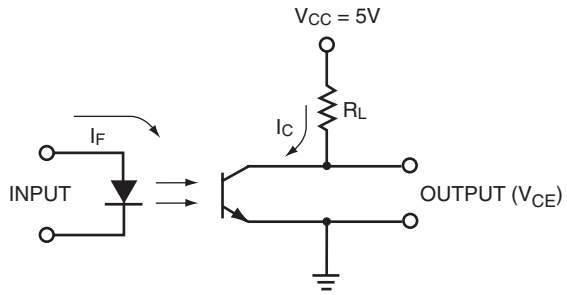


Figure 19. Switching Time Test Circuit

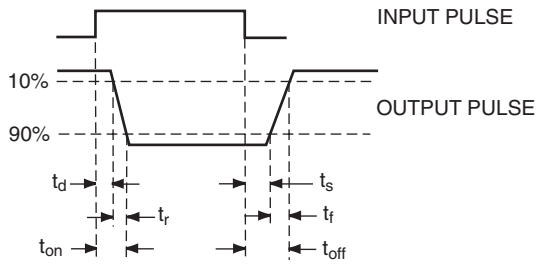
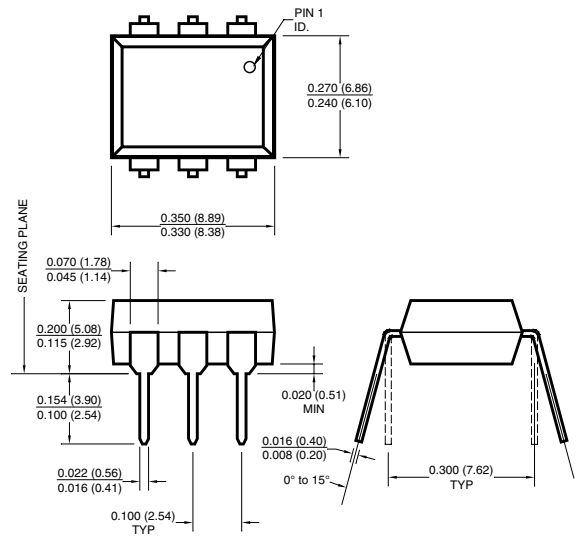


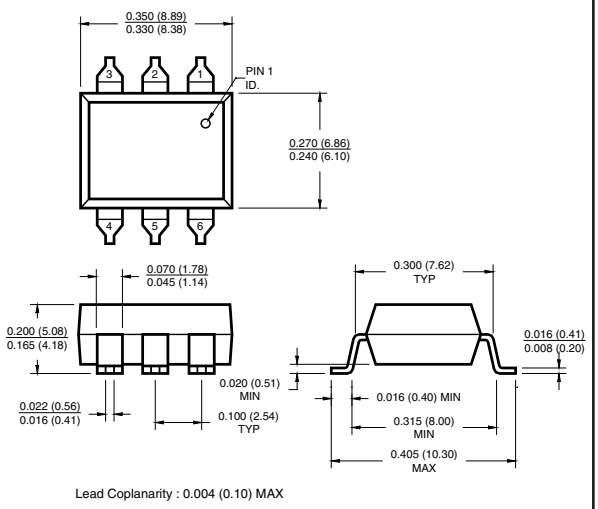
Figure 20. Switching Time Test Circuit

Black Package (No -M Suffix)

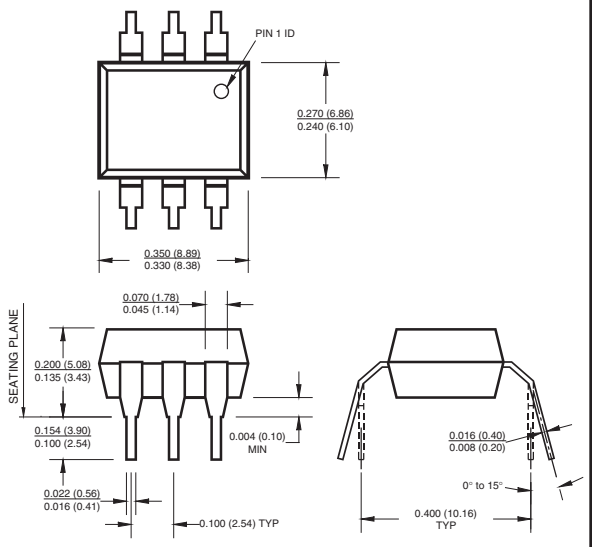
Package Dimensions (Through Hole)



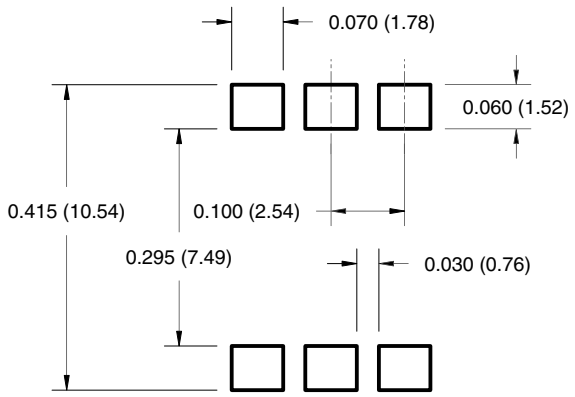
Package Dimensions (Surface Mount)



Package Dimensions (0.4” Lead Spacing)



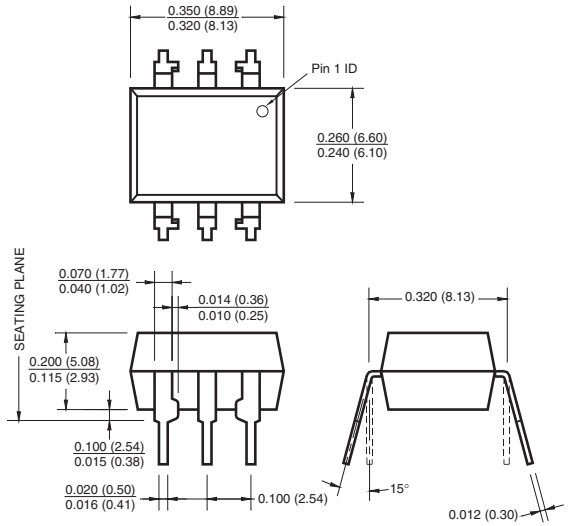
Recommended Pad Layout for Surface Mount Leadform (Black Package Only)



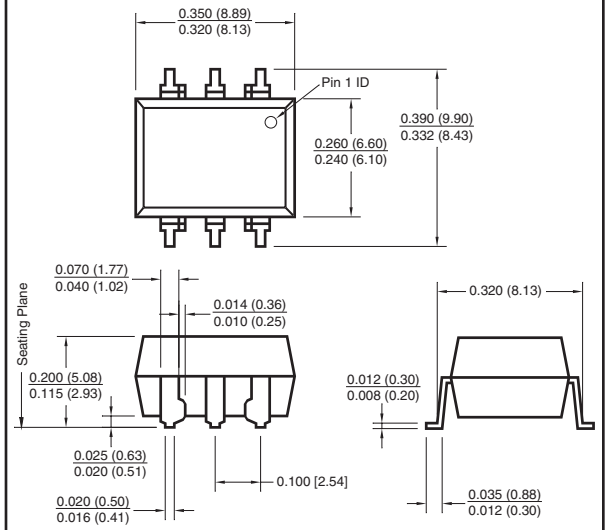
NOTE
All dimensions are in inches (millimeters)

White Package (-M Suffix)

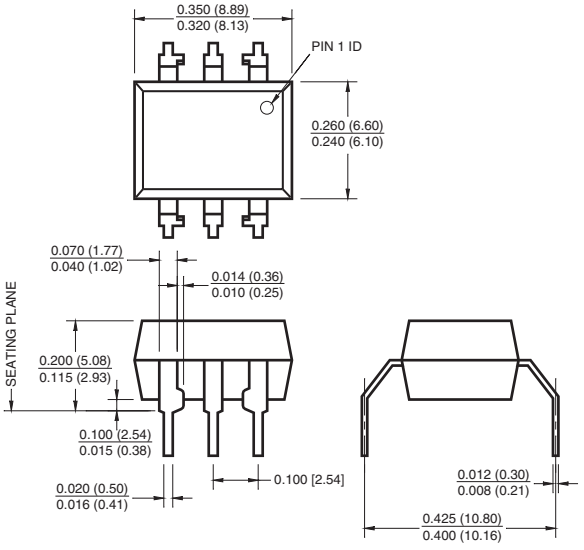
Package Dimensions (Through Hole)



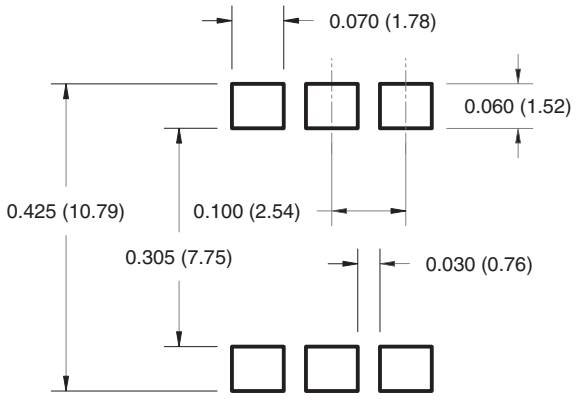
Package Dimensions (Surface Mount)



Package Dimensions (0.4” Lead Spacing)



Recommended Pad Layout for Surface Mount Leadform (White Package Only)

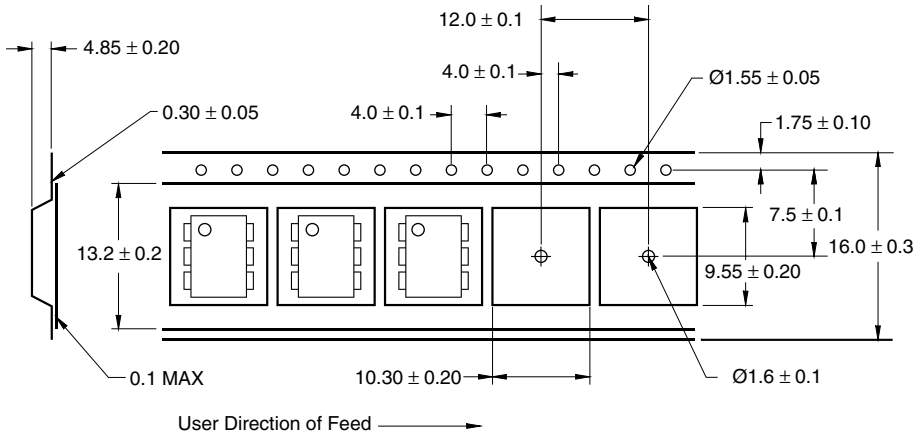


NOTE
All dimensions are in inches (millimeters)

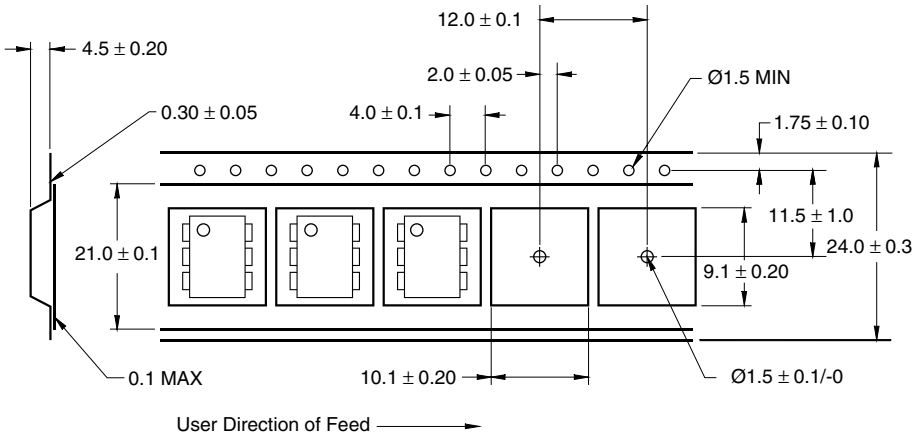
Ordering Information

Option	Black Package (No Suffix)	White Package (-M Suffix)	Description
	Order Entry Identifier		
S	.S	S	Surface Mount Lead Bend
SD	.SD	SR2	Surface Mount; Tape and reel
W	.W	T	0.4" Lead Spacing
300	.300	V	VDE 0884
300W	.300W	TV	VDE 0884, 0.4" Lead Spacing
3S	.3S	SV	VDE 0884, Surface Mount
3SD	.3SD	SR2V	VDE 0884, Surface Mount, Tape & Reel

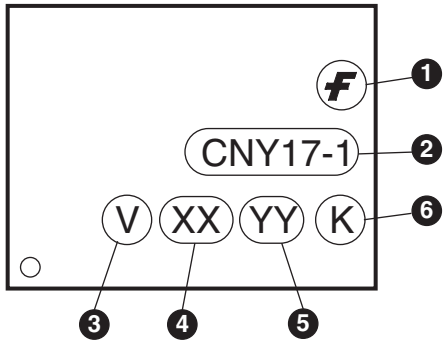
Carrier Tape Specifications (Black Package, No Suffix)



Carrier Tape Specifications (White Package, -M Suffix)

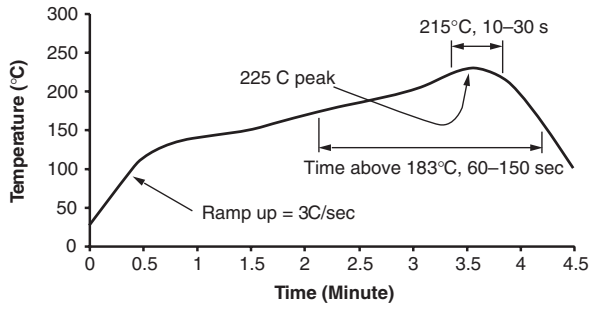


Marking Information



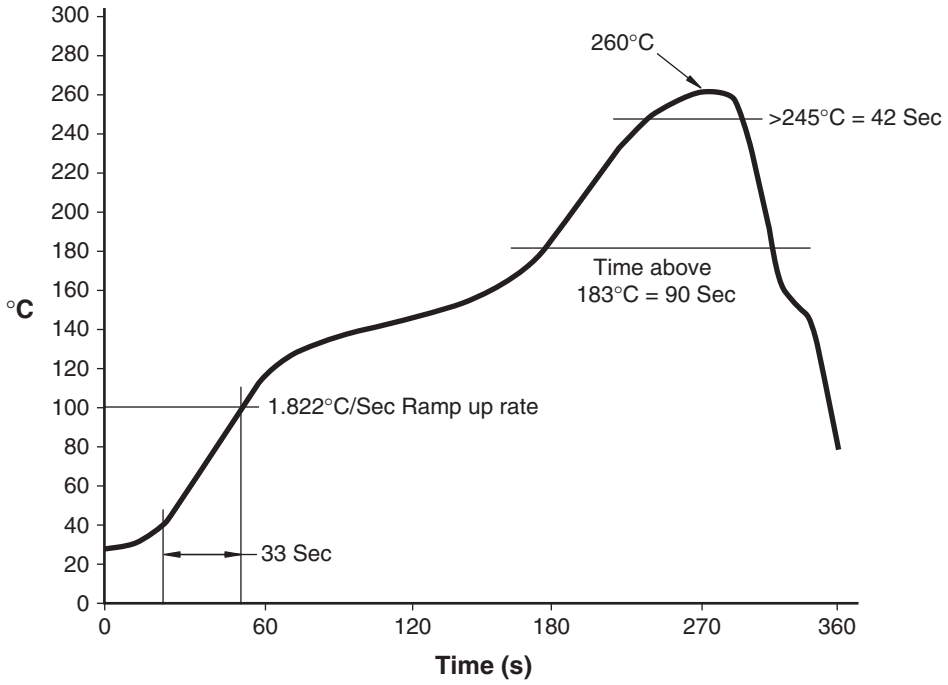
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digits year code, e.g., ‘03’
5	Two digit work week ranging from ‘01’ to ‘53’
6	Assembly package code

Reflow Profile (Black Package, No Suffix)



- Peak reflow temperature: 225°C (package surface temperature)
- Time of temperature higher than 183°C for 60–150 seconds
- One time soldering reflow is recommended

Reflow Profile (White Package, -M Suffix)



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Definition of Terms

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